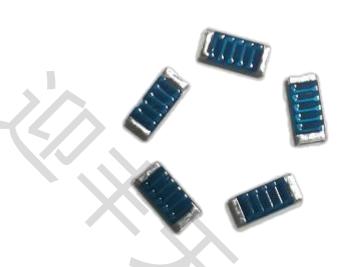
5.0 x 2.2 x 1.0 (mm) WiFi/Bluetooth Ceramic Chip Antenna (YF500C) Engineering Specification

1. Product Number

YF 5020 H2 R 2G4502

1 2 3 4 5



(1)Product Type	Chip Antenna
(2) Size Code	5.0x2.2mm
(3) Type Code	H2
(4) Packing	Tape and reel
(5) Frequency	2.45GHz



Prepared by : harry	Designed by : andy	Checked by : andy	Approved by : oli	ver
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2. Features

- *Stable and reliable in performances
- *Low temperature coefficient of frequency
- *Low profile, compact size
- *RoHS compliance
- *SMT processes compatible

3. Applications

- *Bluetooth earphone systems
- *Hand-held devices when WiFi /Bluetooth functions are needed, e.g., Smart phone.
- *IEEE802.11 b/g/n
- *ZigBee
- *Wireless PCMCIA cards or USB dongle

4. Description

Ying feng chip antenna series are specially designed for WiFi/Bluetooth applications. Based on yingfeng proprietary design and processes, this chip antenna has excellent stability and sensitivity to consistently provide high signal reception efficiency.

5. Electrical Specifications (40 x 40 mm² ground plane)

5-1. Electrical Table

-	Characteristics	Specifications	Unit
Outline D	imensions	5.0x2.2x1.0	mm
Working I	requency	2400~2500	MHz
VSWR		2 Max.	
Impedano	ce	50	Ω
Polarizati	on	Linear Polarization	
Peak 2.5 (t		2.5 (typical)	dBi
Gain	Efficiency	78 (typical)	%

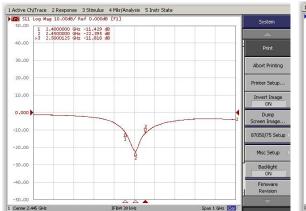
5-2. Return Loss & VSWR

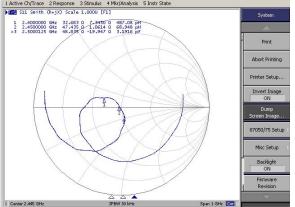


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Return Loss (S₁₁)

Smith Chart(S₁₁)



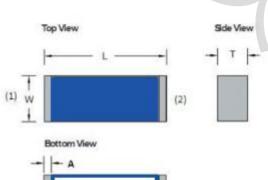


6 Outline Dimensions of Antenna & Evaluation Board (unit: mm)

6-1. Antenna Dimensions

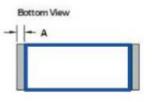
Configuration and Dimensions:

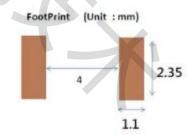
Dimension and Terminal Configuration



Dimension (mm)					
L 5.0 +-0.20					
W	2.2+- 0.20				
Т	1.0 +-0.20				
Α	0.40+-0.20				

No.	Terminal Name
1	Feeding
2	Soldering



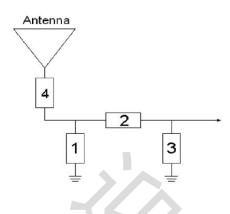




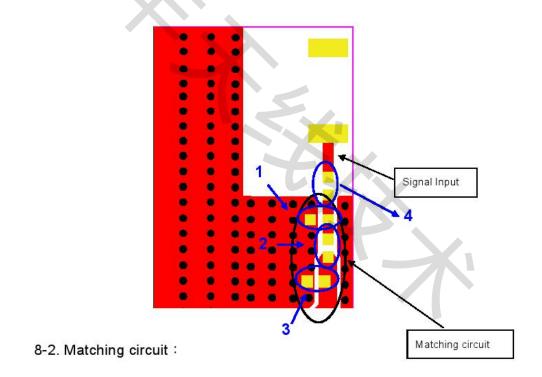
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	m) WiFi/Bluetooth Ceramic Chip	DOCUMENT	YF5022H2R2	2G4502	REV.	
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6-2-2. Matching Circuit:

With the following recommended values of matching and tuning components, the center frequencies will be about 2450 MHz at our standard 40x40 mm² evaluation board. However, these are reference values, may need to be changed when the circuit boards or part vendors are different.

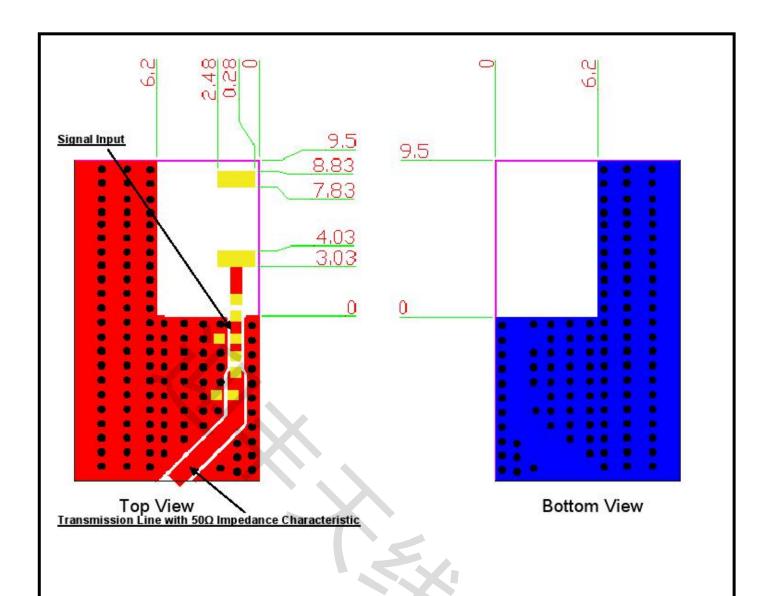


	System Matching Circuit Component								
Location	Location Description								
1	N/A*	i.e.							
2	3.3nH, (0402)	DARFON							
3	1.5pF, (0402)	MURATA							
4	0Ω, (0402)	:-							



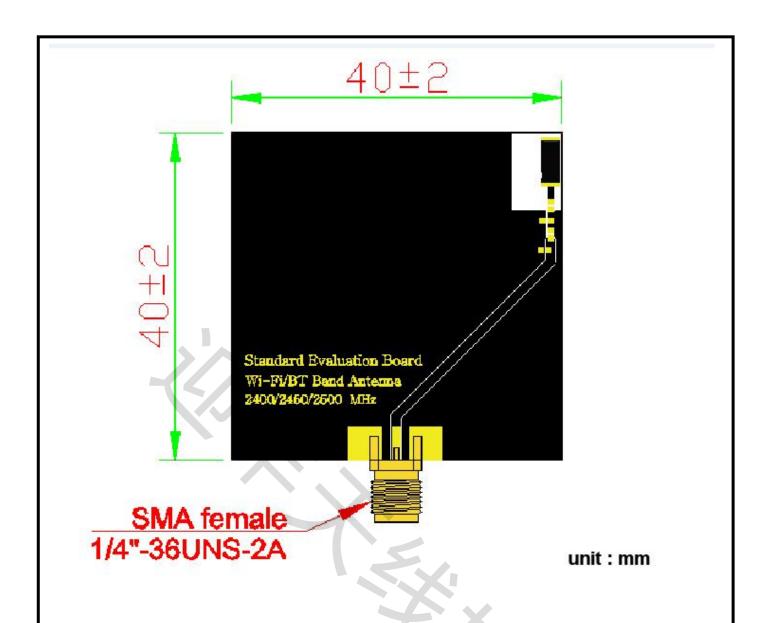


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7.Radiation Pattern (40x 40 mm² ground plane)

7-1. 3D Gain Pattern @ 2450 MHz

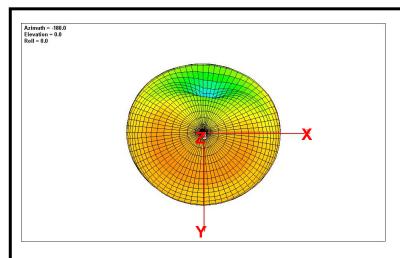


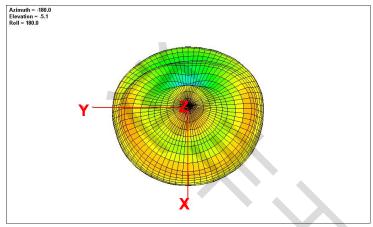
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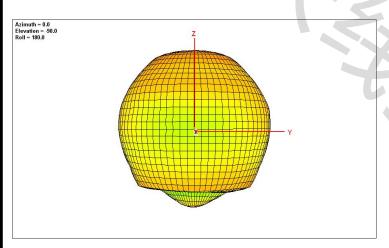
Prepared by : harry Designed by : andy Checked by : andy Approved by : oliver

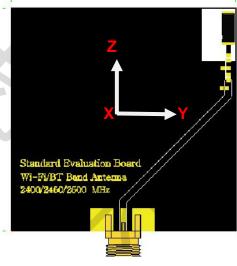
TITLE : 5.0 x2.2 x 1.0mm) WiFi/Bluetooth Ceramic Chip Antenna (YF500C Engineering Specification NO.

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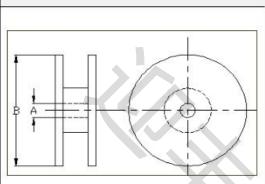
Prepared by : harry	Designed by : andy	Checked by : andy	Approved by : oliver		
TITLE: 5.0 x2.2 x 1.0mn	n) WiFi/Bluetooth Ceramic Chip	DOCUMENT	VF5022H2R2G4502	REV.	

Antenna (YF500C Engineering Specification NO. B

7-2. 3D Efficiency Table

Frequency(MHz)	2400	2410	2420	2430	2442	2450	2460	2470	2480	2490	2500
Efficiency (dB)	-1.4	-1.0	-0.9	-0.7	-0.7	-0.8	-0.9	-1.1	-1.2	-1.3	-1.4
Efficiency (%)	70.8	71.7	72.3	74.4	74.5	75.0	74.0	73.6	72.1	71.6	70.5
Gain (dBi)	1.9	2.1	2.3	2.4	2.5	2.5	2.4	2.3	2.2	2.1	1.8

Taping Specifications

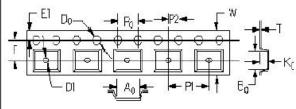


Reel

Checking note	Index	Spec (mm)
Internal diameter of reel	Α	60.20 ± 0.50
External diameter of reel	В	178 ± 1.00

Quantity/per reel	3000 pcs	
T	Plastic	
Tape material	(embossed)	

Taping Blister Tape



Checking note	Index	Spec (mm)
Sprocket hole	D0	1.50 +0.10/-0.00
Distance sprocket hole to outside	E1	1.75 ± 0.10
Distance sprocket hole to pocket	F	5.50 ± 0.05
Distance sprocket hole to sprocket hole	P0	4.00 ± 0.10
Distance pocket to pocket	P1	4.00 ± 0.10
Distance sprocket hole to pocket	P2	2.00 ± 0.05
Tape width	W	12.00 +0.30/-0.10
Pocket width nominal clearance	A0	2.28 ± 0.13
Pocket length nominal clearance	В0	5.70 ± 0.13
Pocket depth minimum clearance	КО	1.58 ± 0.10
Thickness of tape	T	0.23 ± 0.02



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Antenna (YF500C Engineering Specification

DOCUMENT NO.

YF5022H2R2G4502

REV.

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Reliability Table

Test Item Procedure		Requirements Ceramic Type	Remark (Reference)	
Electrical Characterization		Fulfill the electrical specification	User Spec.	
Thermal Shock	1. Preconditioning: 50 ± 10℃ / 1 hr , then keep for 24 ± 1 hrs at room temp. 2. Initial measure: Spec: refer Initial spec. 3. Rapid change of temperature test: -30℃ to +85℃; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107	
Temperature Cycling	1. Initial measure: Spec: refer Initial spec. 2. 100 Cycles (-30°C to +85°C), Soak Mode=1 (2 Cycle/hours). 3. Measurement at 24 ± 2Hours after test condition.	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104	
High Temperature Exposure	1. Initial measure: Spec: refer Initial spec. 2. Unpowered; 500hours @ T=+85℃. 3. Measurement at 24 ± 2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108	
Low Temperature Storage	1. Initial measure: Spec: refer Initial spec. 2. Unpowered: 500hours @ T= -30 ℃. 3. Measurement at 24 ± 2 hours after test.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108	
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: 235 ± 5°C b. Dipping time: 3 ± 0.5s	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/2 4.10	
Soldering Heat Resistance (RSH)	Preheating temperature: 150 ± 10°C. Preheating time: 1~2 min. Solder temperature: 260 ± 5°C. Dipping time: 5 ± 0.5s	No Visible Damage.	IEC 60384-21/2 4.10	
Vibration	5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at comers of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz	No Visible Damage.	MIL-STD-202 Method 204	
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213	
Humidity Bias	1. Humidity: 85% R.H., Temperature: 85 ± 2 °C. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2hrs after test condition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106	



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Board Flex (SMD)	1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm) 2. Apply the load in direction of the arrow until bending reaches 2 mm. Support Fladus 540 Protee to exset bending force Displacement.	No Visible Damage.	AEC-Q200 005
Adhesion	Force of 1.8Kg for 60 seconds. radius 0,5 mm DUT wide thickness sheat force	No Visible Damage Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.	AEC-Q200 006
Physical Dimension	Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.	In accordance with specification.	JESD22 JB100



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